FEATURES AND SPECIFICATIONS

PCI Express* Connectors

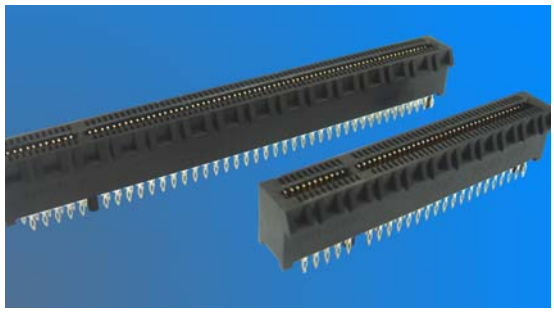
Molex's PCI Express connector offers greater signaling bandwidths for today's workstation and server applications*

PCI Express is a third generation I/O architecture. PCI-SIG recently updated PCI Express specifications to greater signaling bandwidth. Unlike the previous version in which the PCI bus is implemented via a multi-drop parallel architecture, PCI Express now incorporates a point-to-point signaling using differential pairs operating at 2.5 Gbps. PCI Express provides adequate bandwidth to support developing I/O such as Infiniband and 10G fiber channel.*

Molex's press fit version of PCI Express provides an alternative for customers who require solderless termination on PCBs which have a high layer count.

All Molex PCI Express connectors are compliant with PCI-SIG specifications. For more information on these specifications please see www.pcisig.com*

78028
Vertical Press fit



Features and Benefits

- *High-temperature thermoplastic housing for lead-free processing*
- *Keying design ensures correct mating of card module to edge card connector*
- *Press fit termination allows solderless termination on high layer count PCBs*
- *Complies with PCI-SIG industry specifications ensure connectors support all PCI Express module cards available in the market*
- *Ridge design will be compatible with module cards that require a retention clip for secure retention*

SPECIFICATIONS

Reference Information
Packaging: Tray
UL File No.: Pending
CSA File No.: Pending
Mates With : PCI Express® module card*
Designed In: mm

Electrical
Voltage: 50 Volts AC (RMS)/DC
Current: 1.1 Amps/pin
Contact Resistance: 30 milliohms max
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min

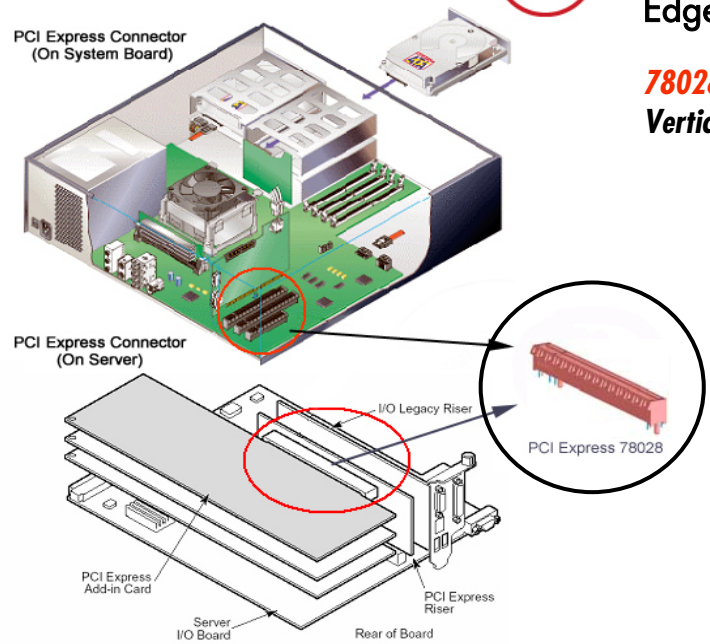
Mechanical
Max Terminal Retention Force: 2.94 N min/Terminal
Mating Force: 1.15 N max/contact pair
Un-Mating Force: 0.15 N min/contact pair
Durability: 50 Cycles

Physical
Housing: High Temperature Nylon, Black, UL 94V-0
Contact: Copper Alloy
Plating:
Contact Area — 0.76 µm Gold or 0.38 µm Gold
Solder Tail Area — Tin
Underplating — Nickel
PCB Thickness: See Ordering Tables
Operating Temperature: - 55 °C to +85 °C

PCI Express, ExpressModule, and PCI-SIG are trademarks of PIC-SIG

Markets and Applications

- Servers
- Desktop
- Mobile
- Networking and Communications



PCI Express EdgeCard Connector

78028
Vertical Press fit

Ordering Information

Lead Free Order Number	Circuits	Plating Thickness	PC Tail Length	Recommended PCB Thickness
78028-0008	98	0.76µm (30µ")	2.54mm (.100")	2.3mm (.090")
78028-0108			2.79mm (.110")	2.6mm (.100")
78028-1108			3.43mm (135")	3.2mm (.125")
78028-0018		0.38µm (15µ")	2.54mm (.100")	2.3mm (.090")
78028-0118			2.79mm (.110")	2.6mm (.100")
78028-1118			3.43mm (135")	3.2mm (.125")
78028-0016	164	0.76µm (30µ")	2.54mm (.100")	2.3mm (.090")
78028-0116			2.79mm (.110")	2.6mm (.100")
78028-1116			3.43mm (135")	3.2mm (.125")
78028-0026		0.38µm (15µ")	2.54mm (.100")	2.3mm (.090")
78028-0126			2.79mm (.110")	2.6mm (.100")
78028-1126			3.43mm (135")	3.2mm (.125")

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